

Docket No. IRV1.PAU.53

Patent Application

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:

Pepe, et al.

Serial No.: 09/938,686

Filed: October 30, 2001

For: METHOD OF MAKING
STACKABLE LAYERS
CONTAINING ENCAPSULATED
INTEGRATED CIRCUIT CHIPS
WITH ONE OR MORE
OVERLAYING INTERCONNECT
LAYERS

Examiner: Hung K. Vu

Group Art Unit: 2811

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Irvine, California

February 19, 2004

AMENDMENT AFTER FINAL

Mail Stop AF
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Dear Sir:

Please enter the following amendment in response to the Office Action dated August 21, 2003. A request for a three-month extension of time and appropriate fees are enclosed. If necessary, please charge Deposit Account No. 01-1960.

VI. SUMMARY

Based on the above amendments and accompanying remarks, Applicants respectfully submit that all pending claims, 2-11, 13-16, 34-36, 40-41, and 43-44, are in condition for allowance and earnestly solicits a notice thereof. Applicant encourages the Examiner to telephone the undersigned attorney if it appears that a telephone conference would facilitate allowance of the application.

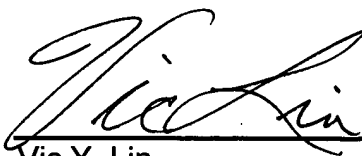
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I hereby certify that this correspondence is being deposited with the United States Postal Service as first class mail in an envelope addressed to: Mail Stop AF, Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450 on February 19, 2004
Angela Williams



Signature
February 19, 2004

Respectfully submitted,



Vic Y. Lin

Registration No. 43,754

Myers Dawes Andras & Sherman LLP

19900 MacArthur Blvd, Suite 1150

Irvine, CA 92612

(949) 223-9600